

# SOT470-3

plastic thermal enhanced low profile quad flat package; 100 leads; exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HLQFP100
<b>Package type industry code</b>	HLQFP100
<b>Package style descriptive code</b>	HLQFP (thermal enhanced low profile quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-7-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	[tbd]	1.7	mm
A <sub>2</sub>	package height	1.55	-	1.6	1.65	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	100	-	

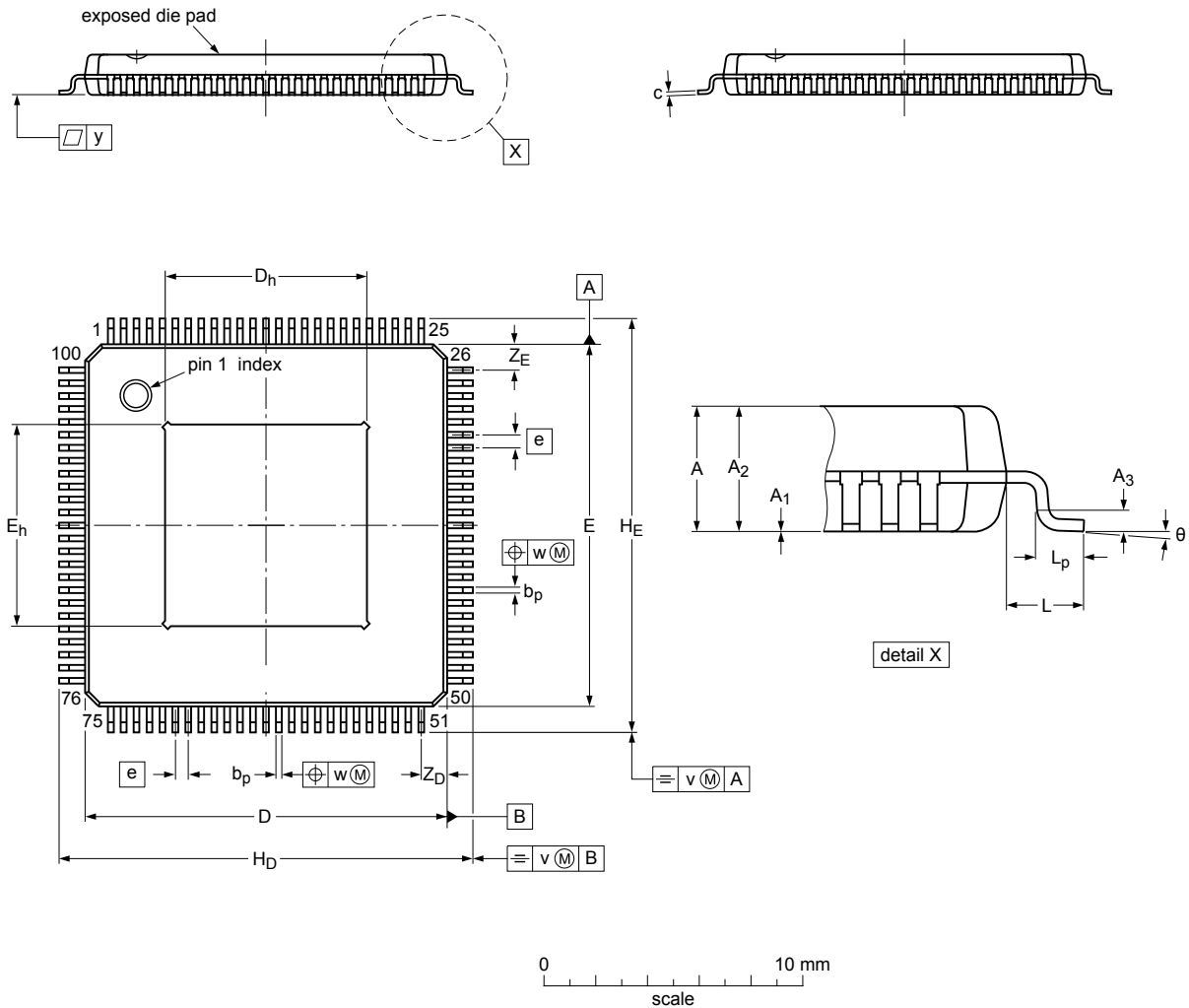


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## 2. Package outline

HLQFP100: plastic, thermal enhanced low profile quad flat package; 100 leads; body 14 x 14 x 1.6 mm; exposed die pad

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Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
max	1.7	0.05	1.65		0.27	0.20	14.1	7.9	14.1	7.9		16.15	16.15		0.75				1.15	1.15	7°
mm nom		0	1.60	0.25	0.22	0.15	14.0	7.8	14.0	7.8	0.5	16.00	16.00	1.0	0.60	0.2	0.08	0.08	1.00	1.00	
min		-0.05	1.55		0.17	0.09	13.9	7.7	13.9	7.7		15.85	15.85		0.45				0.85	0.85	0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

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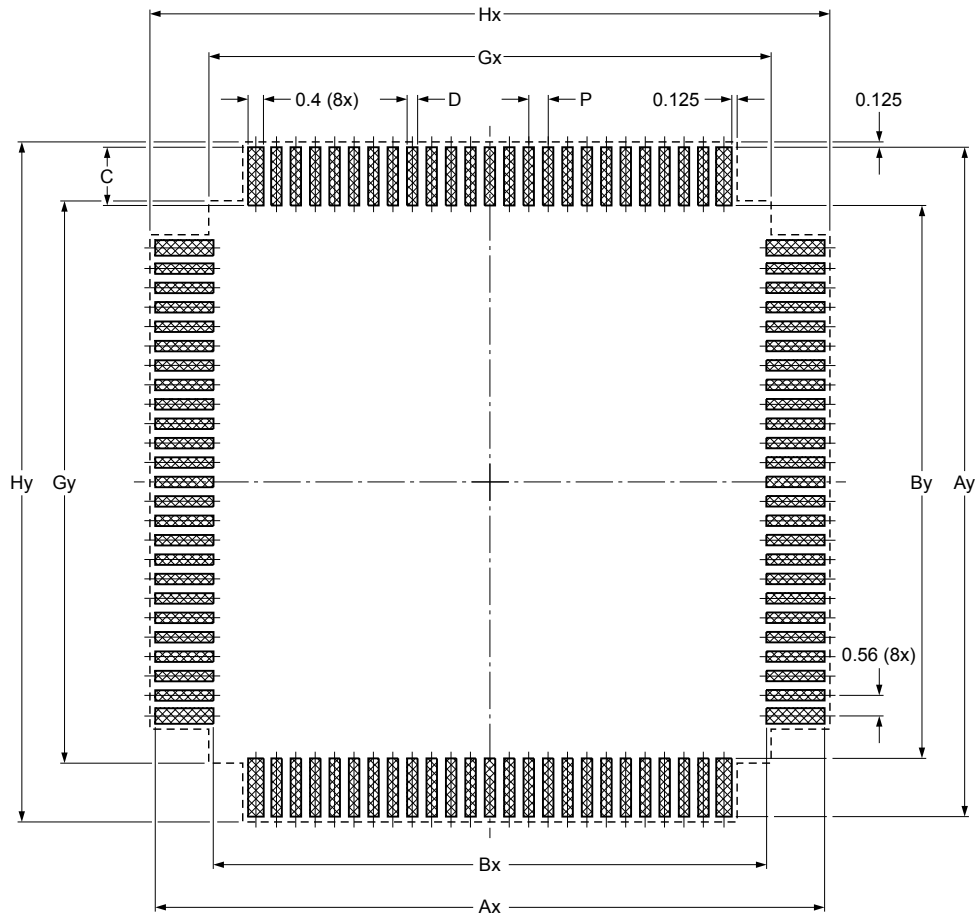
Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT470-3					-15-06-02- 15-07-06

Fig. 1. Package outline HLQFP100 (SOT470-3)

### 3. Soldering

Footprint information for reflow soldering of HLQFP100 package

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- solder land
- occupied area
- solder paste deposit
- solder land plus solder paste

Dimensions in mm recommended stencil thickness: 0.1 mm

P	Ax	Ay	Bx	By	C	D	Gx	Gy	Hx	Hy
0.5	17.3	17.3	14.3	14.3	1.5	0.28	14.5	14.5	17.55	17.55

Issue date ~~15-07-10~~  
15-07-16

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Fig. 2. Reflow soldering footprint for HLQFP100 (SOT470-3)

## 4. Legal information

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